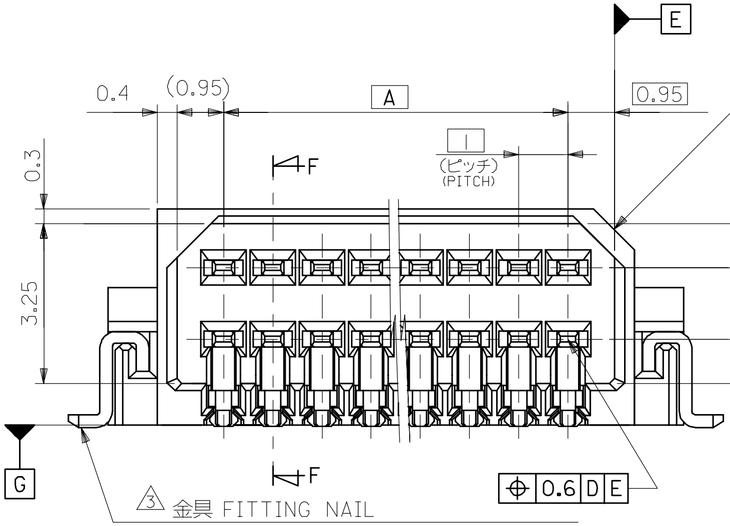
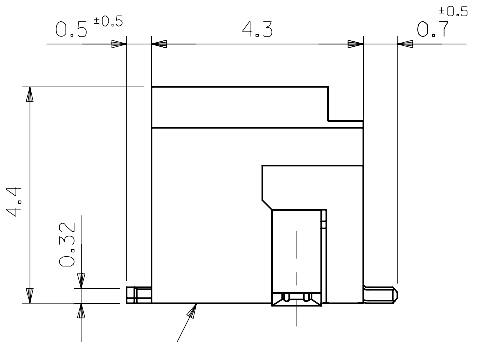
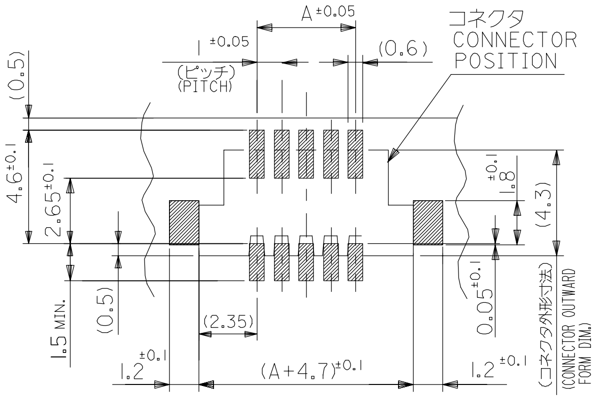


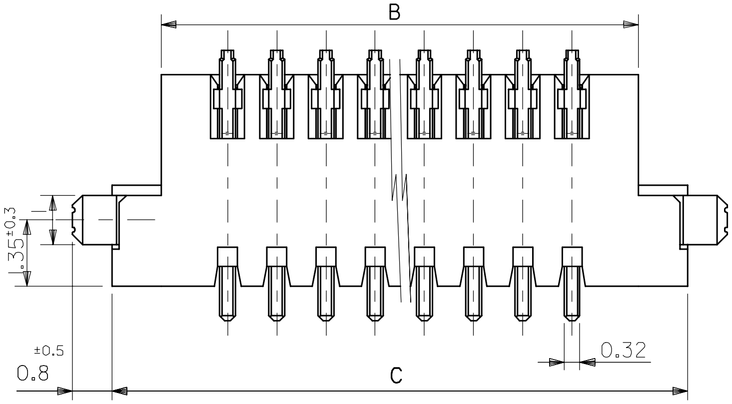
（リン青銅、
ニッケル下地　錫メッキ
t=0．25）（PHOSPHOR BRONZE
TIN OVER NICKEL PLATING
t=0.25）

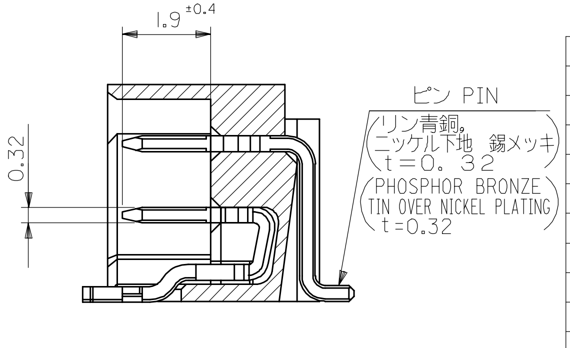


ウエハー WAFER
（ナイロン46　，ガラス入り
UL94V-0
(46NYLON , UL-94V-0)）



パターン参考寸法（マウント面）
RECOMMENDED DIM. FOR P.C.BOARD
MOUNTING PATTERN (REF.)





SECT.F-F

C	B	A	MATERIAL NO.	極数 CIRCUIT
18.7	16.7	14	53268-3029	30
17.7	15.7	13	-2829	28
16.7	14.7	12	-2629	26
15.7	13.7	11	-2429	24
14.7	12.7	10	-2229	22
13.7	11.7	9	-2029	20
12.7	10.7	8	-1829	18
11.7	9.7	7	-1629	16
10.7	8.7	6	-1429	14
9.7	7.7	5	-1229	12
8.7	6.7	4	-1029	10
7.7	5.7	3	-0829	8
6.7	4.7	2	53268-0629	6

MODEL NO.　53268-**29

注記 NOTES.

1. 嵌合相手：52365 シリーズ
MATES WITH : 52365 SERIES
2. ハウジングの底面 G からの金具及びターミナル半田付面のズレ量は
上方向0．1MAX．下方向0．15MAX．とする。
MISALIGNMENT OF SOLDER TAIL TIP AND FITTING NAIL FROM G
: UPPER DIRECTION 0.1mmMAX.
: LOWER DIRECTION 0.15mmMAX.
⚠3 パターンハクリ止メ用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.
4. 本製品は53268-**20の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53268-**20.
5. ソルダーテールおよびフィッティングネールの平坦度は 0.15MAX. とする。
SOLDER TAILS AND FITTING NAILS COPLANARITY TO BE 0.15MAX.

REV	DESCRIPTION
A	REVISED EC NO: J2006-2470 DRWN:YAOYAGI 2006/02/01 CH'KD:YMAEDA 2006/02/03 APPR:NUKITA 2006/02/06

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

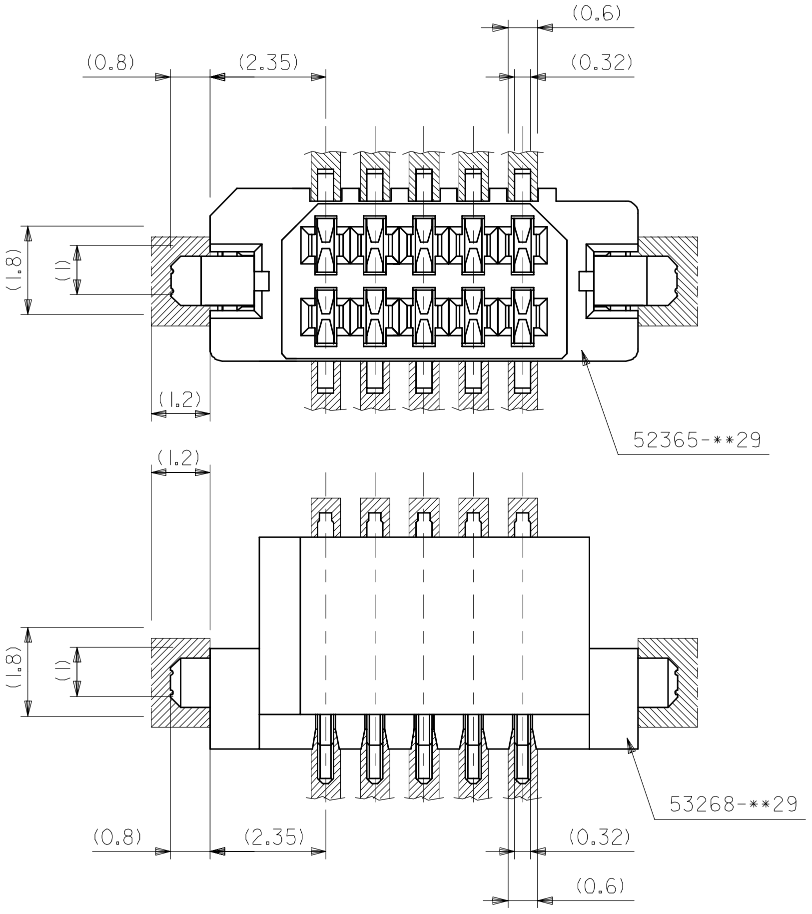
DIMENSION STYLE	SCALE	DESIGN UNITS	
MM ONLY	---	METRIC	THIRD ANGLE PROJECTION

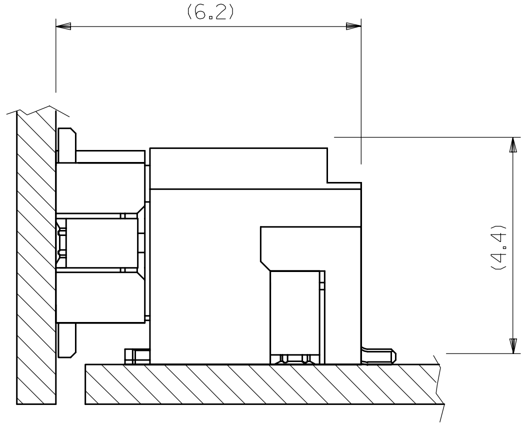
	DATE
DRAWN BY Y.WADA	2004/05/17
CHECKED BY M.SASAO	2004/05/17
APPROVED BY M.SASAO	2004/05/17

TITLE
1.0 B/B CONN.WAFER ASS'Y
R/A SMT
-LEAD FREE-

molex MOLEX INCORPORATED

MATERIAL NO. SEE CHART
DOCUMENT NO. SD-53268-009
SHEET NO. 1 OF 2
SIZE A3





基板取付推奨レイアウト
RECOMMENDED P.C.BOARD LAYOUT

MODEL NO.	53268-**29

REV	DESCRIPTION
A	REVISED EC NO: J2006-2470 DRWN:YAOYAGI 2006/02/01 CH'KD:Y.MAEDA 2006/02/03 APPR:NUKITA 2006/02/06

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION

DRAWN BY Y.WADA	DATE 2004/05/17
CHECKED BY M.SASAO	DATE 2004/05/17
APPROVED BY M.SASAO	DATE 2004/05/17

TITLE
1.0 B/B CONN.WAFER ASS'Y
R/A SMT
-LEAD FREE-

molex MOLEX INCORPORATED

MATERIAL NO.	DOCUMENT NO.	SHEET NO.
SEE SHEET 1 OF 2	SD-53268-009	2 OF 2

SIZE A3

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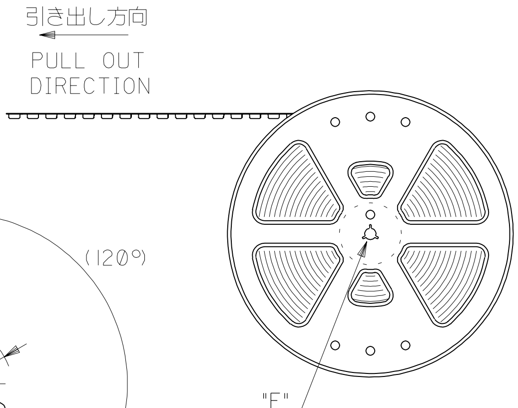
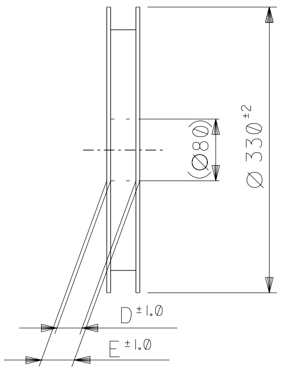
tb_frame_A3_J_ME_S
Rev. D 2004/04/02

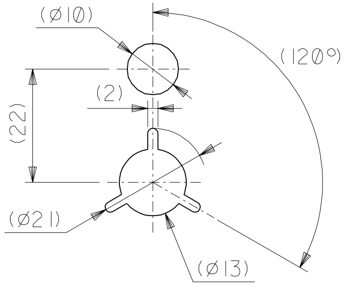
EN-02JA(021)

ENG. NO SD-53268-010

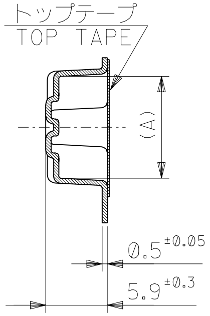
EDP NO. —//—



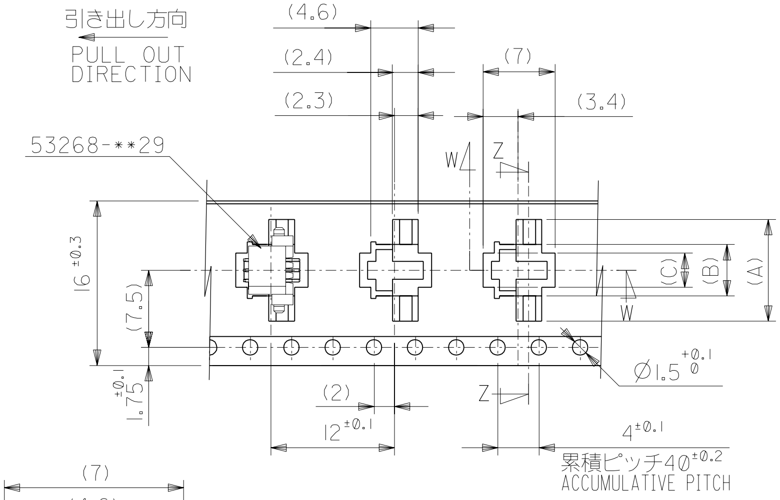


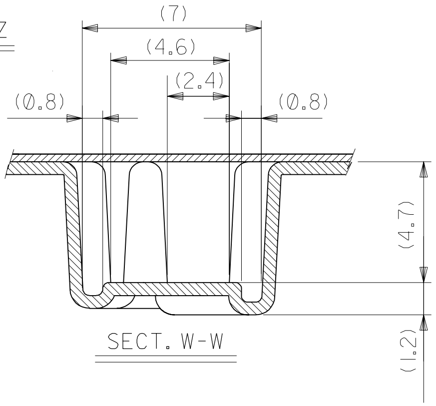


DETAIL "F"



SECT. Z-Z

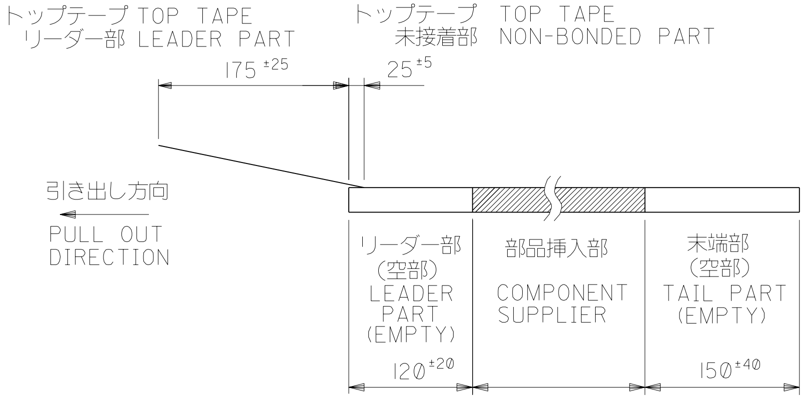




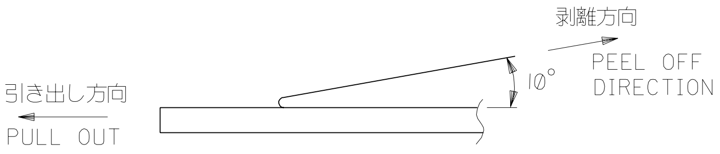
SECT. W-W

注記 NOTES

1. 梱包数量： 1000 個／リール　NUMBER OF CONNECTORS: 1000PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH



3. トップテープの剥離強度：（剥離方向は下図参照）
0.1N ～ 1.3N {10gf ～ 130gf}　尚、本規格値は、出荷時に適用。
（但し、輸送時に剥離が発生しない事。）
PEELING OFF FORCE OF TOP TAPE : 0.1N ～ 1.3N {10gf ～ 130gf}
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION



4. 材料 DIRECTION　MATERIAL
キャリアテープ：ポリプロピレン（ＰＰ）　CARRIER TAPE:POLYPROPYLENE
トップテープ：ＰＥＴ，ＰＥ，ＰＥＦ　TOP TAPE:PET,PE,PEF
リール：ポリスチレン（ＰＳ）　REEL:POLYSTYRENE(PS)
<リサイクル材を含む>　<RECYCLE MATERIAL CONTAINED>
5. 本製品は 53268-**91 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53268-**91.

16	21.4	17.4	3.1	5	9.9	53268-0670	6
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

角度 ANGLE	±3°
30 以上 OVER	±0.3
10 以上 OVER 30 未満 UNDER	±0.25
10 未満 UNDER	±0.2
一般公差 GENERAL TOLERANCES	

記号 LTR	変更内容 REVISION RECORD	DR. / CHK.	日付 DATE
0	新規作成 RELEASED (J2004-4258)	Y.W / M.S	'04/05/17

REVISE ONLY ON CAD SYSTEM

材料 MATERIAL　注記参照 SEE NOTES
仕上げ FINISH —//—
適用電線範囲 WIRE RANGE —//—
被覆外径 INS. RANGE —//—
DRAWN BY '04/05/17 Y.WADA
CHK'D BY '04/05/17 M.SASAO
APP'D BY '04/05/17 M.SASAO
尺度 SCALE —//—

MODEL NO. 53268-**70
molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
EDP. NO. —//—
ENG. NO. (SHEET 1 OF 2) SD-53268-010　REV 0
TITLE 名称 1.0 B+B Conn Wafer Assy RA SMT Embstp Pkg -LEAD FREE-

:MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING

SD-53268-010.S01

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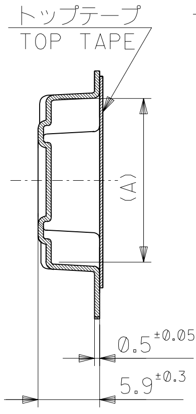
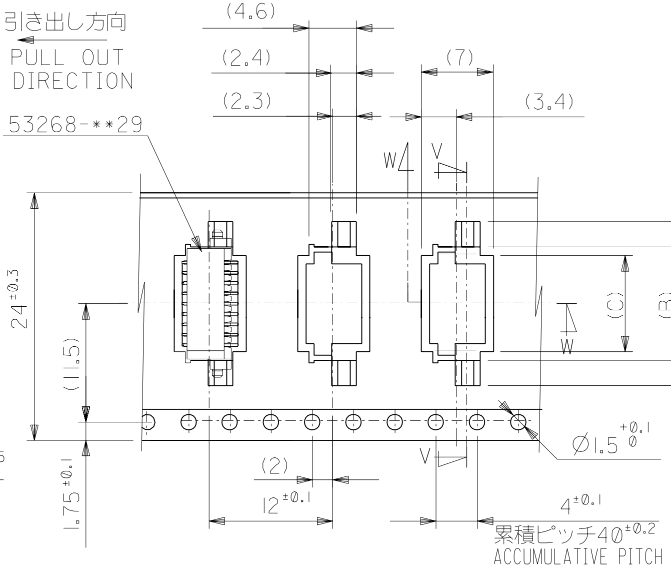
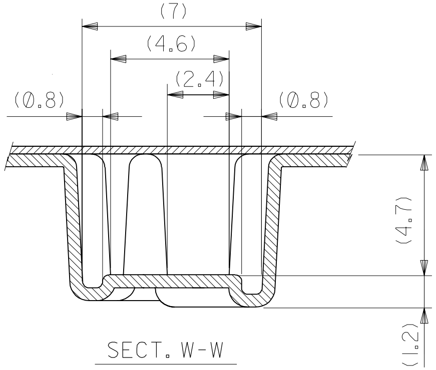
MXJ-8

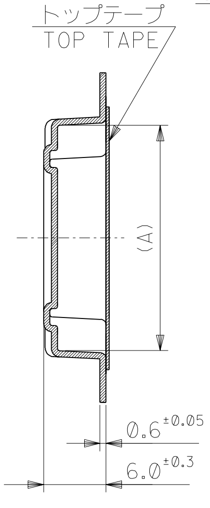


SECT. V-V

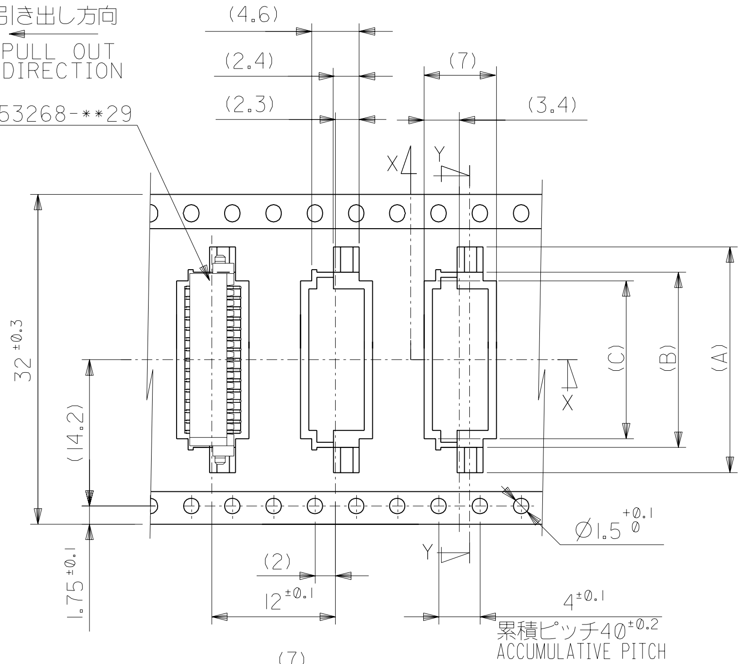


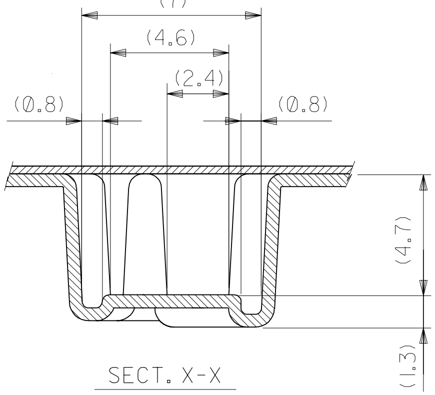


SECT. W-W



SECT. Y-Y





SECT. X-X

キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT
32	37.4	33.4	15.15	17	21.9	53268-3070	30
			14.15	16	20.9	53268-2870	28
			13.15	15	19.9	53268-2670	26
			12.15	14	18.9	53268-2470	24
24	29.4	25.4	11.1	13	17.9	53268-2270	22
			10.1	12	16.9	53268-2070	20
			9.1	11	15.9	53268-1870	18
			8.1	10	14.9	53268-1670	16
			7.1	9	13.9	53268-1470	14
			6.1	8	12.9	53268-1270	12
			5.1	7	11.9	53268-1070	10
			4.1	6	10.9	53268-0870	8

角度 ANGLE	±3°
30 以上 OVER	±0.3
10 以上 OVER 30 未満 UNDER	±0.25
10 未満 UNDER	±0.2

一般公差 GENERAL TOLERANCES

記号 LTR	変更内容 REVISION RECORD	DR.	CHK.	日付 DATE
0	新規作成 RELEASED (J2004-4258)	Y.W	M.S	'04/05/17

REVISE ONLY ON CAD SYSTEM

材料 MATERIAL
SHEET 1 OF 2 参照
REFER TO SHEET 1 OF 2

仕上げ FINISH —//—

適用電線範囲 WIRE RANGE —//—

被覆外径 INS. RANGE —//—

DRAWN BY '04/05/17 Y.WADA

CHK'D BY '04/05/17 M.SASAO

APP'D BY '04/05/17 M.SASAO

尺度 SCALE —//—

MODEL NO. 53268-**70

molex MOLEX-JAPAN CO.,LTD.
日本モレックス株式会社

EDP. NO. —//—

ENG. NO. (SHEET 2 OF 2) SD-53268-010
REV 0

TITLE 名称
1.0 BtB Conn Wafer Assy
RA SMT Embstp Pkg
-LEAD FREE-

:MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING